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May 23, 2005

### VIA EXPRESS MAIL NO. EV627509822US

MAIL STOP - AMENDMENT Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Re:

Application No.: 10/814,532

Title: Integrated Circuit Stacking System and Method

Filing Date: March 31, 2004

Docket No.: 254-094-PCT2-USCIP-1

AK Matter No.: 153673

### Dear Commissioner:

Please find enclosed for filing the following:

1. Response to Office Action Mailed on May 18, 2005 (7 pages); and

2. A return postcard for confirmation of receipt.

The Commissioner is hereby authorized to charge any fees deemed to be due or credit any overpayment to Deposit Account No. 50-0897, upon which the undersigned is authorized to sign.

Please return the postcard confirming your receipt of the enclosed materials.

Yours truly,

Scott Denko

Registration No. 37,606

JSD/at **Enclosures** 



# Attorney Docket No. 254-094-PCT-2-USCIP-1

**AK Matter No.: 153673** 

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Title:

Integrated Circuit Stacking System and Method

Application No.:

10/814,532

Filing Date:

March 31, 2004

Inventor:

James W. Cady, et al.

Assignee:

Staktek Group, L.P.

Examiner:

Jasmine Jhihan B. Clark

Group:

2815

CERTIFICATE OF MAILING UNDER 37 CFR §1.10

I hereby certify that this paper or fee is being deposited with the United States Postal Service via Express Mail No. EV627509822US addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the day of May, 2005.

Mail Stop - Amendment **Assistant Commissioner for Patents** P.O. Box 1450 Alexandria, VA 22313-1450

# **RESPONSE TO OFFICE ACTION MAILED ON MAY 18, 2005**

Applicants respond as follows to the May 18, 2005 Office Action, in the above-identified patent application:

Amendments to the Claims are reflected in the listing of claims in this paper. Remarks follow the Amendment section of this paper.